

## Type SSP and LSP screed floor boards

Untreated chipboard	Symbol	Test method	Unit	Value
Classification	P5 in acc. with EN 312, boards for load-bearing purposes in damp environments			
Type	Sanded on both sides			
Certification	PEFC-certified			
Gross density	$\rho_a$		kg/m <sup>3</sup>	~715–740
Thermal conductivity	$\lambda_D$		W/mK	0.140
Fire behaviour		EN 13501-1		D-s2, d0
Thickness tolerance within and between the boards		EN 324-1	mm	±0.3
Board moisture		EN 322	%	5–13
Formaldehyde potential category E1		EN 120	mg/100 g	Max. 8.0
Thickness swelling (after 24 hrs)		EN 317	%	10.0
Bending strength		EN 310	N/mm <sup>2</sup>	16.0
Bending elasticity modulus		EN 310	N/mm <sup>2</sup>	2400
Transverse tensile strength		EN 319	N/mm <sup>2</sup>	0.45
Transverse tensile strength after boil test		EN 1087-1	N/mm <sup>2</sup>	0.14
Water vapour permeability (density: 600 kg/m <sup>3</sup> )		EN 13986	$\mu$ , damp $\mu$ , dry	15 50
Degree of sound absorption			250–500 Hz 1000–2000 Hz	0.10 0.25
Swelling and shrinkage in panel plane (Change of board moisture: 1%)			%	0.02–0.05

Expanded rigid polystyrene foam (EPS)	Symbol	Test method	Unit	Value
Gross density	$\rho_a$	SN EN 1602	kg/m <sup>3</sup>	15
Thermal conductivity	$\lambda_D$	SIA V 279	W/mK	0.038
Fire behaviour		VKF	BKZ	5.1
Specific thermal capacity	C		Wh/kgK	0.39
Water vapour diffusion resistance factor	$\mu$	SN EN 12086		40
Compression stress at 10% compression	$\sigma_{10}$	SN EN 826	kPa	≥60
Creep behaviour under pressure (50 years, compression <2%)	$\sigma_c$	SN EN 1606	kPa	≥12
Top application limit temperature, non-weight-bearing			°C	75
Cell content				Air

Expanded rigid polystyrene foam with graphite additive (EPS lambda)	Symbol	Test method	Unit	Value
Gross density	$\rho_a$		kg/m <sup>3</sup>	20
Thermal conductivity	$\lambda_D$		W/mK	0.030
Fire behaviour		DIN 4102		B1
Compression stress at 10% compression			kPa	≥100
Compression stress at 2% compression			kPa	≥20–35
Heat distortion temperature, short-term			°C	95
Heat distortion temperature, long-term			°C	80–85
Water absorption after 28 days underwater storage			Volume per cent	3–4
Water vapour diffusion resistance factor	$\mu$			30–55